

Supporting Information

One-step green synthesis of Cu₂O/CuO@rGO composites for ppt level detection of NO₂ at room temperature

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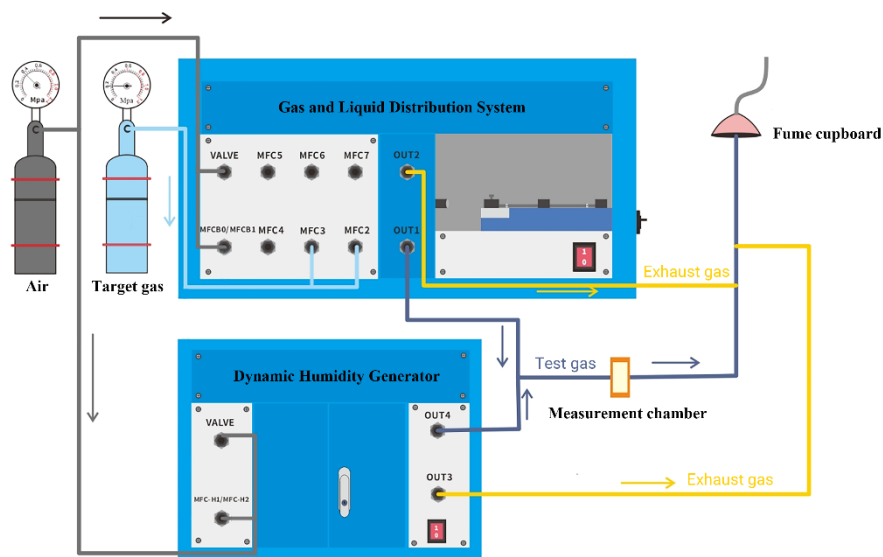


Fig. S1 Schematic diagram of dynamic gas sensitivity test system.

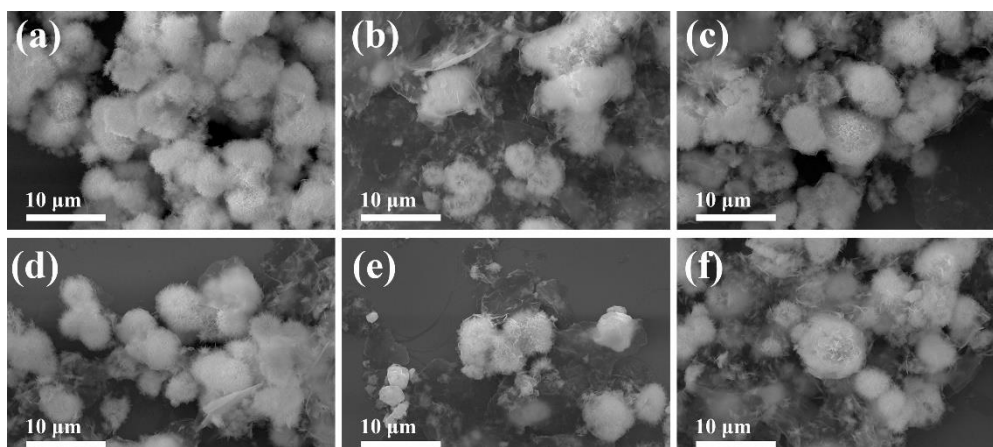


Fig. S2 FE-SEM images of (a) 550Cu₂O/CuO-5; (b) 150Cu₂O/CuO@rGO-5; (c) 300Cu₂O/CuO@rGO-5; (d) 450Cu₂O/CuO@rGO-5; (e) 550Cu₂O/CuO@rGO-5 and (f) 650Cu₂O/CuO@rGO-5.

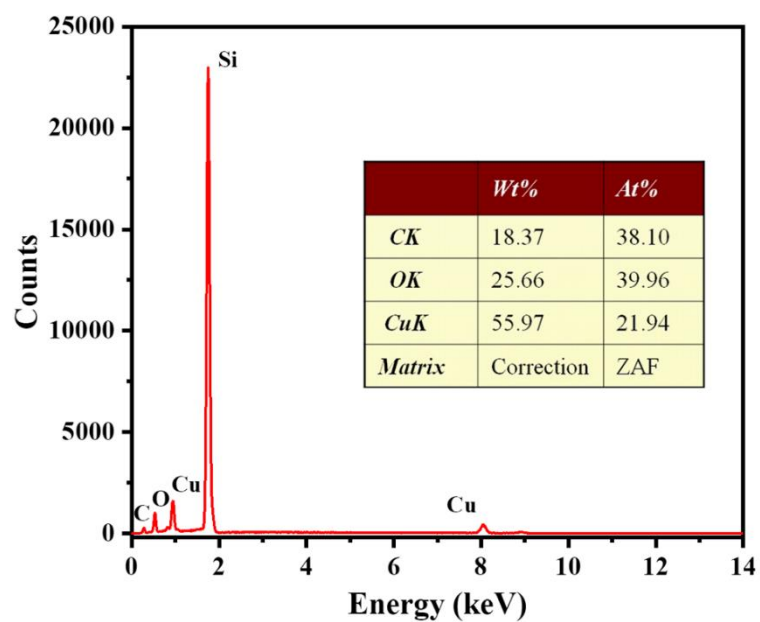


Fig. S3. EDX analysis of the 550Cu₂O/CuO@rGO-5.

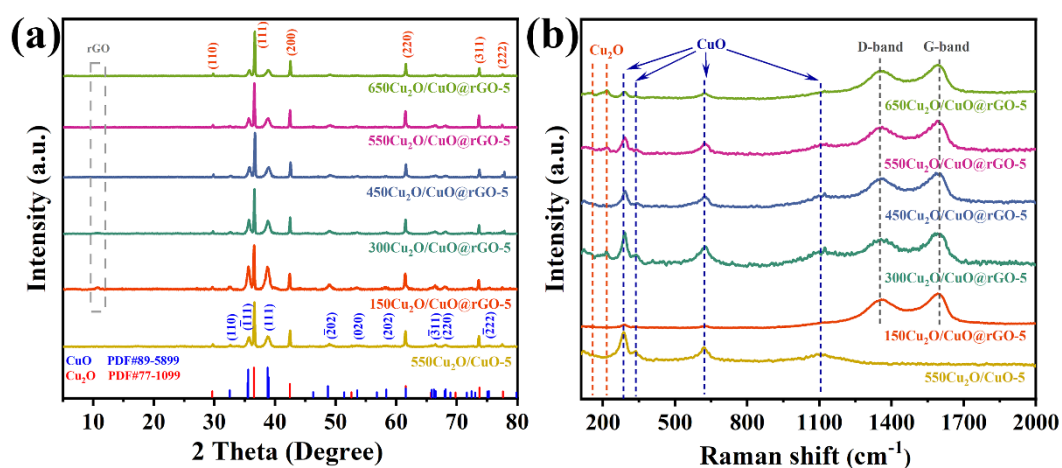


Fig. S4. (a) XRD and (b) Raman spectra of Cu₂O/CuO@rGO-5 composites with different Cu₂O additions.

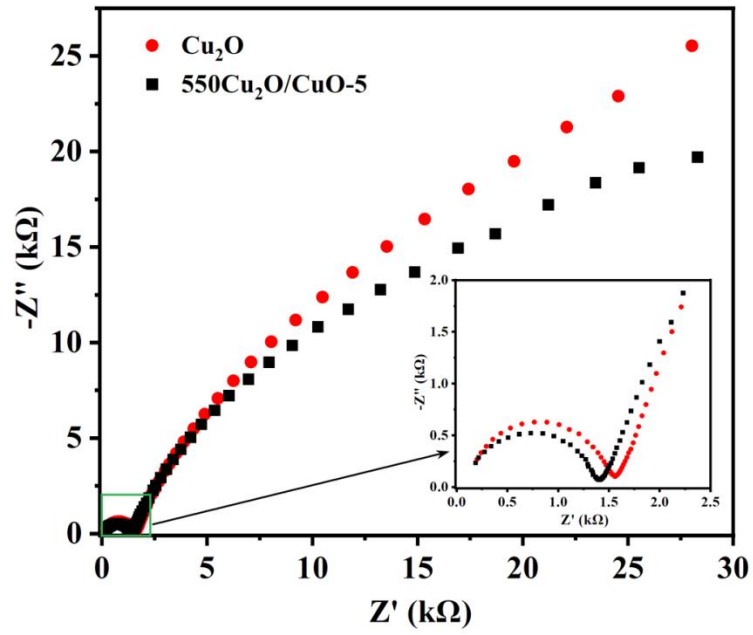


Fig. S5. Electrochemical impedance spectroscopy (Nyquist diagram) of pure Cu₂O and 550Cu₂O/CuO-5 materials.

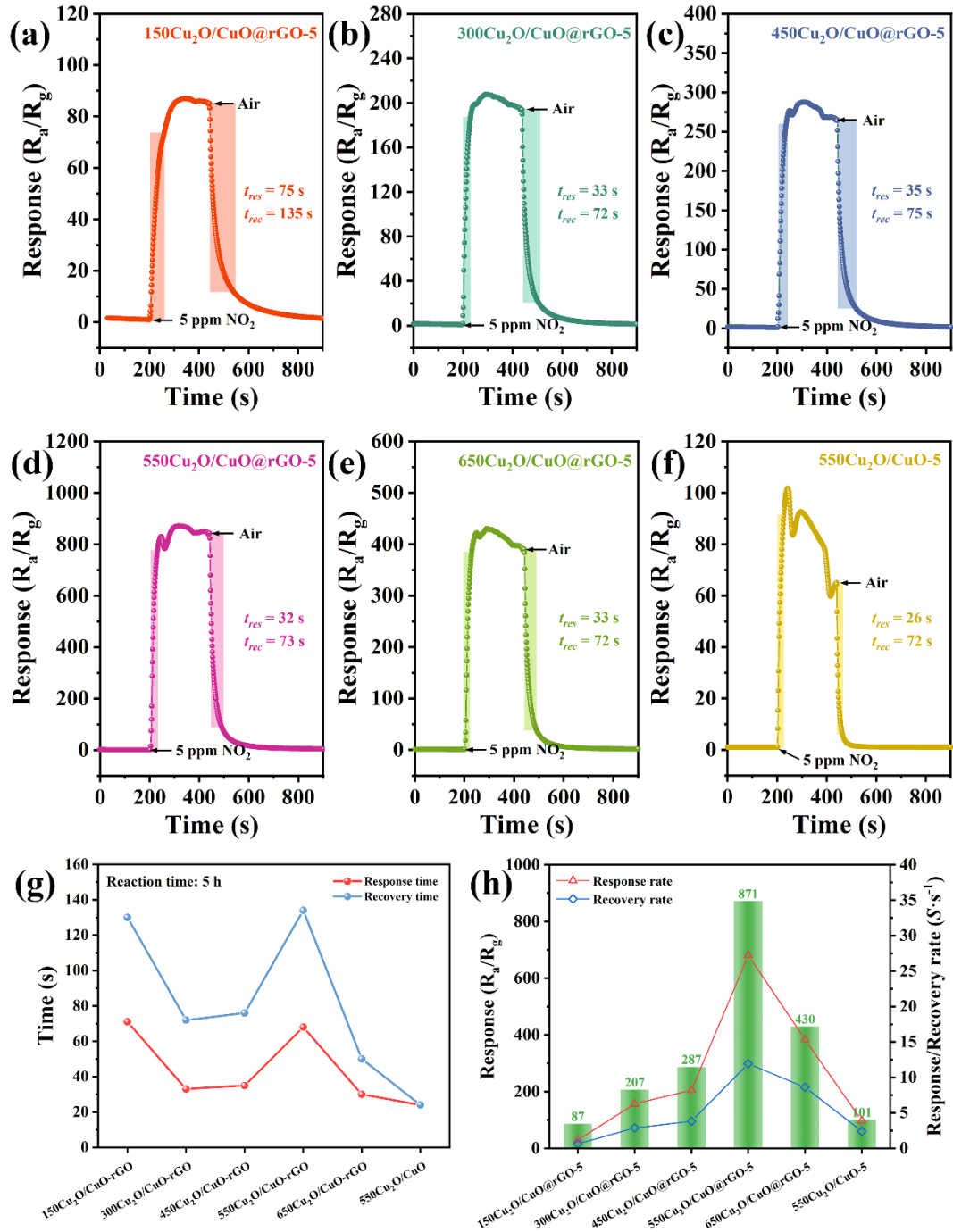


Fig. S6. Dynamic response-recovery curve of (a-e) Cu₂O/CuO@rGO-5 sensors with different Cu₂O additions and (f) 550Cu₂O/CuO sensor to 5 ppm NO₂ at RT; (g) response/recovery time of Cu₂O/CuO@rGO-5 sensors with different Cu₂O additions and 550Cu₂O/CuO sensor with different reaction time to 5 ppm NO₂ at RT; (h) response and response/recovery rate of Cu₂O/CuO@rGO-5 sensors with different Cu₂O additions and 550Cu₂O/CuO sensor with different reaction time to 5 ppm NO₂ at RT.

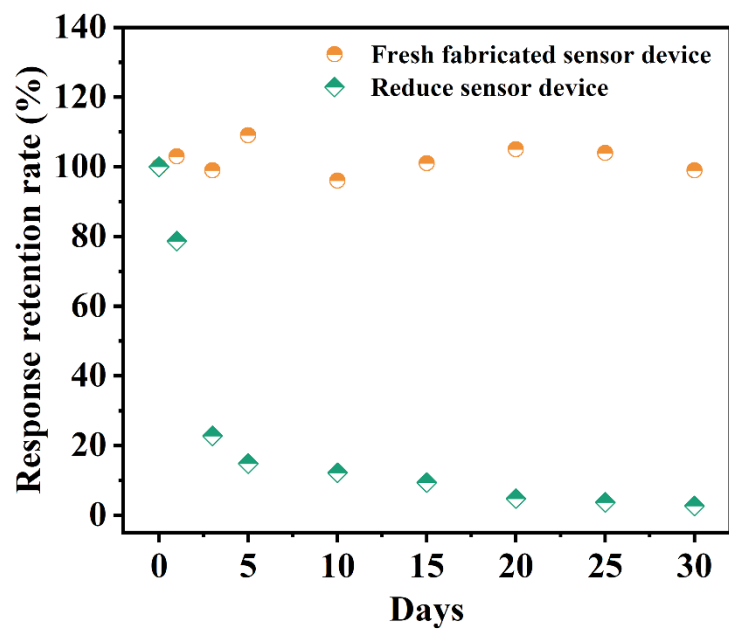
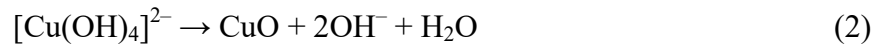
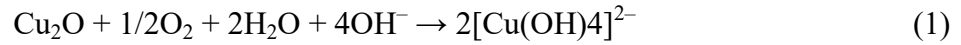


Fig. S7. The stability evaluation of the as-prepared 550Cu₂O/CuO@rGO-5 sensor within one month.

The evolution mechanism of the Cu₂O/CuO materials

The chemical equation of CuO obtained from Cu₂O is shown in Eq. 1-2. The excess OH⁻ in the solution together with O₂ etch the surface of Cu₂O and form [Cu(OH)₄]²⁻ (Eq. 1). However, because [Cu(OH)₄]²⁻ is unstable, it will decompose into CuO and H₂O (Eq. 2). At the same time, it self-assembles around the Cu₂O to form urchin-like Cu₂O/CuO spheres. Similarly, we have added the relevant description in the revised version.



LOD

The sensor noise can be calculated by the change of the relative response of the sensor in the baseline. Ten consecutive data collected before exposure to NO₂ gas were averaged, and the standard deviation (S) calculated using the root mean square deviation (RMSD)¹ formula was 0.00022.

$$\text{RMS}_{\text{noise}} = \sqrt{\frac{S^2}{N}} \quad \#(3)$$

where N is the number of data points. The RMS_{noise} is calculated according to the above Eq. 3 to be 0.000156. According to the definition of detection limit (three times the standard deviation of noise). The slope is 0.00227 from Fig. 8d, so that

$$\text{LOD} = 3 \times \frac{\text{RMS}_{\text{noise}}}{\text{slope}} = 0.0906 \text{ ppb} = 90.6 \text{ ppt} \quad \#(4)$$

Table S1. The peak intensity ratio between Cu₂O and CuO and between D band and G band in Cu₂O/CuO@rGO-5 composites varies with the amount of Cu₂O added.

Sample at different Cu₂O addition amount (mg)	GO	150	300	450	550	650
$I_{\text{Cu}_2\text{O (111)}}/I_{\text{CuO (111)}}$	—	1:0.518	1:0.293	1:0.231	1:0.233	1:0.211
I_D/I_G	1.28	1.16	0.99	0.99	0.98	0.92

Table S2. NO₂ response of Cu_xO-based and rGO-based sensors in different work and the gas sensor in this work.

Material	Synthesis method/ temperature	Work Temperature	Response	τ_{res}/τ_{rec}	LOD
Cu ₂ O-CuO ²	One -step/180 °C	187 °C	10.2 (1 ppm)	35/47*	—
CuO-Co ₃ O ₄ ³	Multi-step/450 °C	160 °C	37.86% (10 ppm)	158/738*	—
CuO/ZnO ⁴	Multi-step/400 °C	RT (30 °C)	337% (5 ppm)	18/32	155 ppb
BiVO ₄ /Cu ₂ O/rGO ⁵	Multi-step/180 °C	60 °C	8.1 (1 ppm)	51.3/87.5*	100 ppb
Cu ₂ O/rGO ⁶	Multi-step/200 °C	RT	67.80% (2 ppm)	~440/490	82 ppb
CuO/rGO ⁷	Multi-step/80 °C	RT (23 °C)	400.80% (5 ppm)	6.8/55.1*	50 ppb
CuO/rGO ⁸	One-step/25 °C	RT	74395.2 (50 ppm)	30/270	100 ppb
CuO/rGO ⁹	One-step/180 °C	RT	30% (50 ppm)	Irreversible	150 ppb
rGO/Cu ₂ O ¹⁰	Multi-step/100 °C	RT	5.2 (1 ppm)	29.2/76.8	32 ppb
550Cu₂O/CuO@rGO-5 ^{This work}	One-step/25 °C	RT (25 °C)	871 (5 ppm)	35/73	90.6 ppt

* Representing that τ_{res}/τ_{rec} is defined in the literature as 90% of the change in resistance value.

Reference

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